Minutes of Strip CMOS sensor progress report meeting, V.2

*2014-10-14*

*Present: J. John, J. Doppke, M. Warren, R. Nickerson, J. Zhang, R. Turchetta, S. Seidel, T. Hoffman, V. Fadeyev, Z. Liang, C. Buttar*

*Apologies: I. McGregor, A. Grillo*

There was an outstanding question how we pay CERN for the AMS submission.

* Richard promised to follow up on that (done).

Alex and Vitaliy reported on work for the November AMS submission. Herve worked out a scanning code to get up to 8 hits from a region of 8 strips. There was a progress with estimating hit occupancy in such small region by Marco Battaglia. (The previous numbers were for a full reticle chip.) Same as for the previous submission, SLAC and UCSC divided the design efforts. SLAC will design drivers and pixel geometries. Herve will work on data encoding and comparators. It might be a good idea to start communication with CERN foundry services earlier this time.

Renato briefed on the status of TJ submission. They are finishing the chip design at RAL. Had one review in September. Will have a final design review at the end of next week.

Jaya John reported on the test hardware development for HVstripV1. They assembled 4 motherboards. The rest got refurbished (an issue with central cutout). They have 12 more daughterboards (some Al, some Cu). They tested digital signal injection and readout, and it was working!

* Everybody interested should let Jaya John know if they need a motherboard.

There was a short discussion of possible engineering run in early spring with AMS H35 technology. SLAC might be interested to participate in such design with a non-ATLAS project. However, the pixel groups are not (officially). They have a higher radiation hardness requirement, which makes AMS H18 technology a better candidate for them. It is possible that there would be enough support in the pixel community for a less official participation in H35 due to the lesser cost and possibility of making 5th pixel layer. We should probably figure out the definitive interests of the 3 communities in the next month or two, to give the designers time to work on the large ICs.